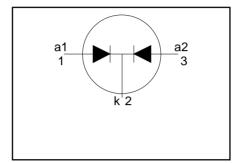
BYV40E series

FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- Reverse surge capability
- High thermal cycling performance
- low profile surface mounting package

SYMBOL



QUICK REFERENCE DATA

$$V_{R} = 150 \text{ V}/200 \text{ V}$$

$$V_{F} \leq 0.7 \text{ V}$$

$$I_{O(AV)} = 1.5 \text{ A}$$

$$I_{RRM} = 0.1 \text{ A}$$

$$t_{rr} \leq 25 \text{ ns}$$

GENERAL DESCRIPTION

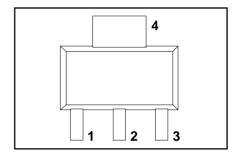
Dual, common cathode, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV40E series is supplied in the SOT223 surface mounting package.

PINNING

PIN	DESCRIPTION		
1	anode 1		
2	cathode		
3	anode 2		
tab	cathode		

SOT223



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
V _{RRM} V _{RWM} V _R	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	$\textbf{BYV40E}$ $T_{sp} \leq 120^{\circ}\text{C}$	1 1 1	-150 150 150 150	-200 200 200 200	V V V
I _{O(AV)} I _{FRM} I _{FSM}	Average rectified output current (both diodes conducting) ¹ Repetitive peak forward current per diode Non-repetitive peak forward current per diode	$T_{sp} \le 132$ °C $t_p = 10$ ms $t_n = 8.3$ ms	- - -	1	.5 .5 .6	A A A
I _{RRM}	Repetitive peak reverse current per diode	sinusoidal; $T_j = 150^{\circ} C$ prior to surge; with reapplied $V_{\text{RWM}(\text{max})}$ $t_p = 2 \ \mu \text{s}; \ \delta = 0.001$	-	0		A
$egin{array}{c} I_{RSM} \ T_{stg} \ T_{j} \ \end{array}$	Non-repetitive peak reverse current per diode Storage temperature Operating junction temperature	t _p = 100 μs	- -65 -		.1 50 50	A °C °C

¹ Neglecting switching and reverse current losses

BYV40E series

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _C	Electrostatic discharge capacitor voltage	Human body model; C = 250 pF; R = 1.5 kΩ	1	8	kV

THERMAL RESISTANCES

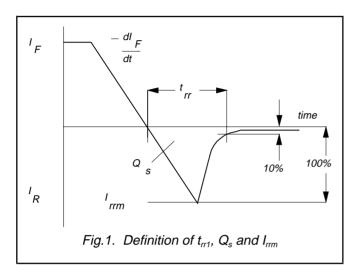
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-sp}	Thermal resistance junction to solder point	one or both diodes conducting	-	-	15	K/W
R _{th j-a}	Thermal resistance junction to ambient	pcb mounted; minimum footprint pcb mounted; pad area as in fig:11		156 70	-	K/W K/W

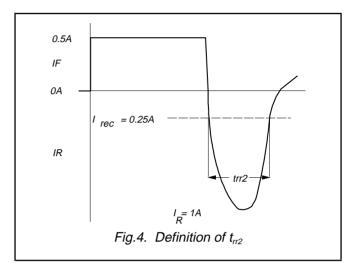
ELECTRICAL CHARACTERISTICS

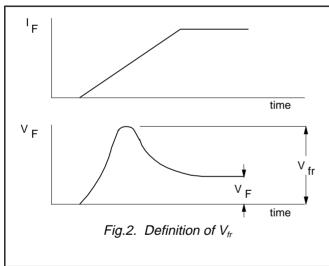
characteristics are per diode at T_i = 25 °C unless otherwise stated

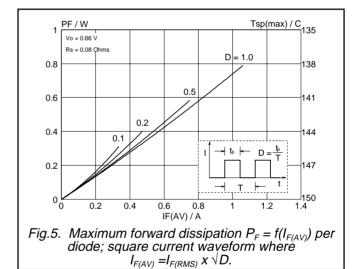
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{F}	Forward voltage	$I_F = 0.5 \text{ A}; T_i = 150^{\circ}\text{C}$	-	0.50	0.7	V
		I _F = 1.5 A	-	0.82	1.0	V
I_R	Reverse current	$\dot{V}_R = V_{RWM}$; $T_i = 100 ^{\circ}C$	-	100	300	μΑ
		$V_R = V_{RWM}$	-	5	10	μΑ
Q_s	Reverse recovery charge	$I_F = 2 \text{ A}; V_R \ge 30 \text{ V}; -dI_F/dt = 20 \text{ A/}\mu\text{s}$	-	-	11	'nС
t _{rr1}	Reverse recovery time	$I_{\rm F} = 1 \text{ A}; V_{\rm R} \ge 30 \text{ V};$	-	-	25	ns
	_	$-dI_{F}/dt = 100 A/\mu s$				
t _{rr2}	Reverse recovery time	$I_F = 0.5 \text{ A to } I_R = 1 \text{ A}; I_{rec} = 0.25 \text{ A}$	-	10	20	ns
$V_{\rm fr}$	Forward recovery voltage	$I_F = 2 \text{ A}; dI_F/d\hat{t} = 20 \text{ A/µs}$	-	3	-	V

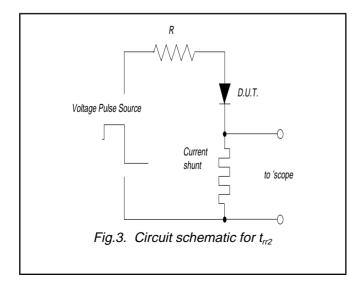
BYV40E series











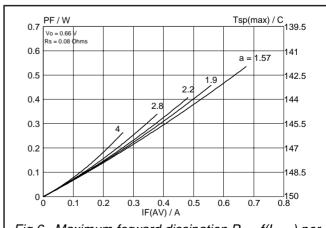
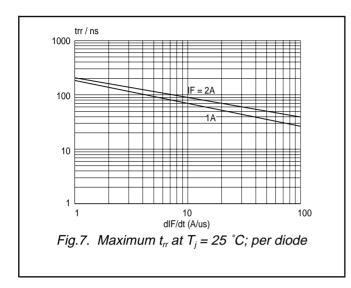
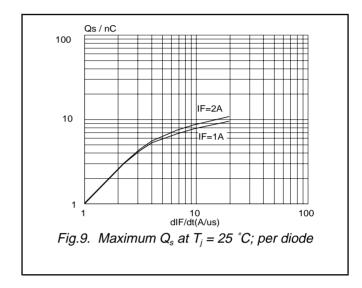


Fig.6. Maximum forward dissipation $P_F = f(I_{F(AV)})$ per diode; sinusoidal current waveform where a = form factor $= I_{F(RMS)} / I_{F(AV)}$.

BYV40E series





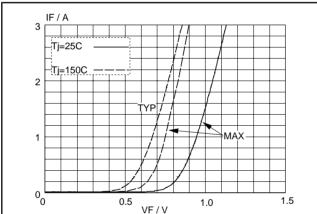


Fig.8. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

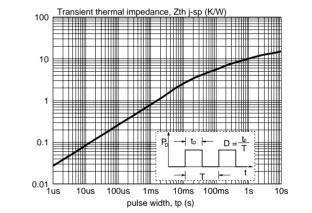
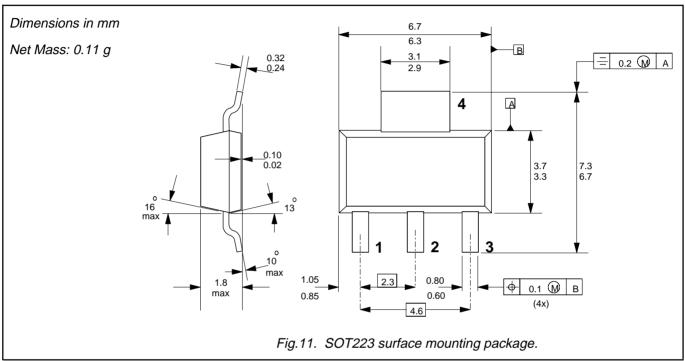


Fig.10. Transient thermal impedance; per diode; $Z_{th j-sp} = f(t_p)$.

BYV40E series

MECHANICAL DATA



- Notes
 1. For further information, refer to Philips publication SC18 " SMD Footprint Design and Soldering Guidelines".
 Order code: 9397 750 00505.
 2. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Rectifier diodes ultrafast, rugged

BYV40E series

DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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